

/ Revised record

F	2017-4				
G	2020-8-28	1			
A	2022.05.19	ALL			

/ Descriptions

SOT-23 N MOS
N-CHANNEL MOSFET in a SOT-23 Plastic Package.

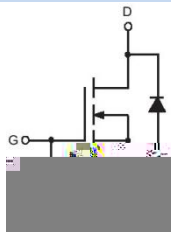
/ Features

2KV
Sensitive gate trigger current and Low Holding current.ESD protected up to 2KV,HF Product.

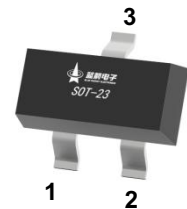
/ Applications

Intended for use in general purpose switching and phase control applications.

/ Equivalent Circuit



/ Pinning



PIN1 G PIN 2 S PIN 3 D

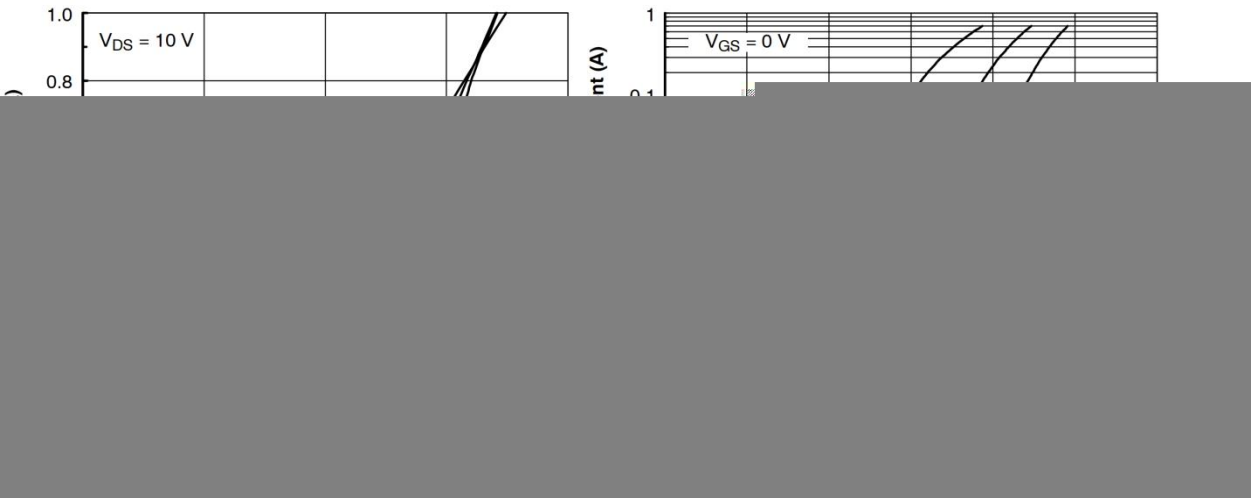
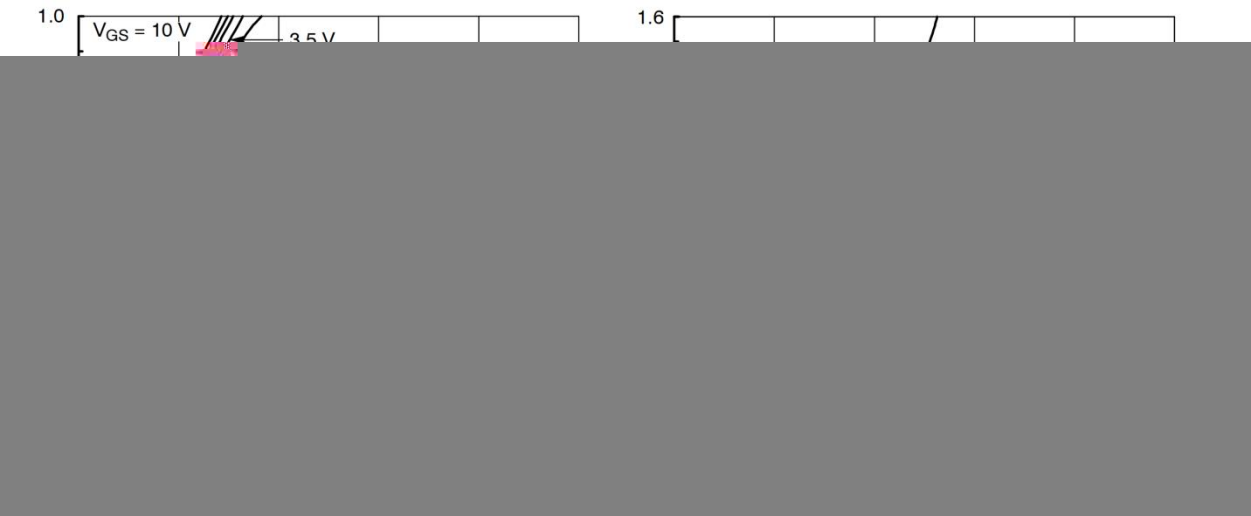
/ Marking

Marking

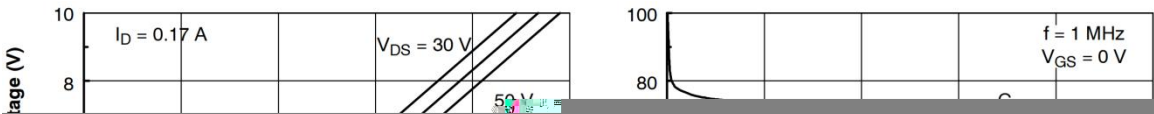
HSA

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Drain Current – Continuous	I_D	170	mA
Drain Current– Pulsed	$I_D(T_C=25^{\circ}C)$	680	mA
Continuous Drain–Source	I_S	170	mA
Gate-Source Voltage	V_{GS}	± 20	V

/ Electrical Characteristic Curve

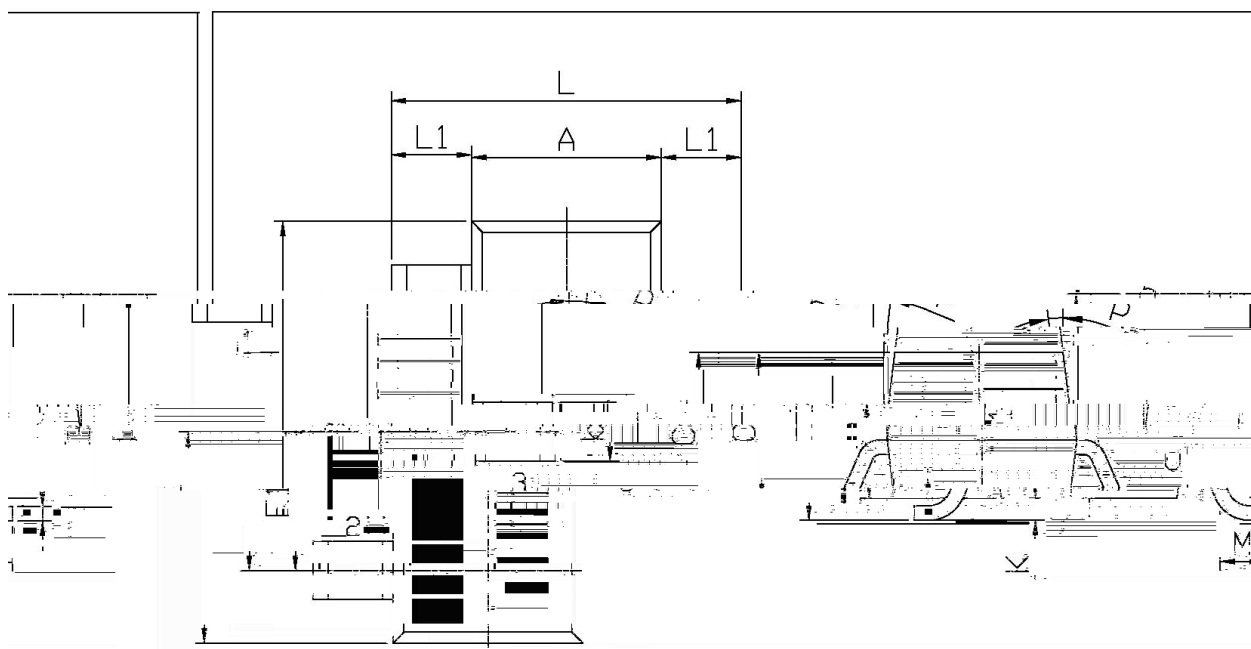


/ Electrical Characteristic Curve



/ Package Dimensions

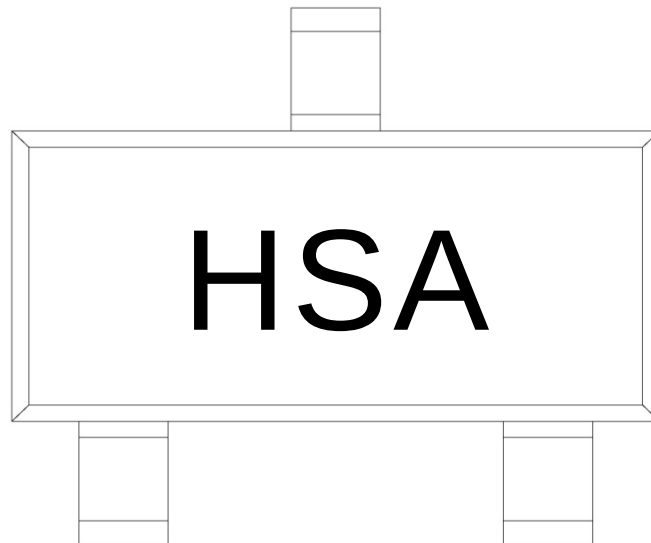
Figure 1: Package Dimensions



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10

P	0.20MIN	7°	E1	0.85	1.05
			b	0.35	0.55

/ Marking Instructions



H

SA

Note:

H: Company Code

SA: Product Type

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**

Note:

- | | | | |
|---|-----------|-------------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ **Resistance to Soldering Heat Test Conditions**

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ **Packaging SPEC.**

/ REEL